

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An ID label comprising:
a label substratum;
an antenna provided over the label substratum;
~~a thin film~~ an integrated circuit device including a ~~thin film~~ transistor, provided over and in contact with the label substratum;
an insulating layer provided over the antenna; and
a wiring provided on the insulating layer;
~~an adhesive layer provided over the wiring;~~
a separating sheet provided over the wiring ~~adhesive layer;~~ and
~~wherein the separating sheet is configured to be peeled from the adhesive layer,~~
wherein the wiring is electrically connected to the antenna through a contact hole formed in the insulating layer, and
wherein the antenna and the ~~thin film~~ integrated circuit device are electrically connected through the wiring.
2. (Canceled)
3. (Currently Amended) The ID label according to claim 1, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin film~~ integrated circuit device.

4. (Currently Amended) The ID label according to claim 1, wherein in the case where protective layers are formed on an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device, it is placed the ~~thin-film~~ integrated circuit device at a position of $(d/2) \pm 30 \mu\text{m}$ or less when a total thickness of the ~~thin-film~~ integrated circuit device and the protective layers is d .

5. (Currently Amended) The ID label according to claim 1, wherein a semiconductor film of the ~~thin-film~~ transistor included in the ~~thin-film~~ integrated circuit device contains hydrogen or halogen of 0.0005 to 5 atomic %.

6. (Currently Amended) The ID label according to claim 1, wherein a size of the ~~thin-film~~ integrated circuit device is 0.09 to 25 mm².

7. (Currently Amended) The ID label according to claim 1, wherein a thickness of the ~~thin-film~~ integrated circuit device is 0.1 to 3 μm .

8. (Currently Amended) An ID label comprising:
a separating sheet;
an internal substratum having a first surface and a second surface, the internal substratum is provided over the separating sheet;
an antenna provided over the first surface of the internal substratum;
~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor, provided over and in contact with the first surface of the internal substratum;
a wiring provided over the second surface of the internal substratum;
a label substratum provided over the ~~thin-film~~ integrated circuit device;
~~an adhesive layer provided between the label substratum and the separating sheet,~~
wherein ~~the separating sheet is configured to be peeled from the adhesive layer,~~

wherein the wiring is electrically connected to the antenna through a contact hole formed in the internal substratum, and

wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

9. (Canceled)

10. (Currently Amended) The ID label according to claim 8, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper portion and a lower portion of the ~~thin-film~~ integrated circuit device.

11. (Currently Amended) The ID label according to claim 8, wherein in the case where protective layers are formed on an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device, it is placed the ~~thin-film~~ integrated circuit device at a position of $(d/2) \pm 30 \mu\text{m}$ or less when a total thickness of the ~~thin-film~~ integrated circuit device and the protective layers is d .

12. (Currently Amended) The ID label according to claim 8, wherein a semiconductor film of the ~~thin-film~~ transistor included in the ~~thin-film~~ integrated circuit device contains hydrogen or halogen of 0.0005 to 5 atomic %.

13. (Currently Amended) The ID label according to claim 8, wherein a size of the ~~thin-film~~ integrated circuit device is 0.09 to 25 mm².

14. (Currently Amended) The ID label according to claim 8, wherein a thickness of the ~~thin-film~~ integrated circuit device is 0.1 to 3 μm .

15. (Currently Amended) An ID card comprising:
a card substratum over which an antenna is formed;
an insulating layer over the antenna;
a wiring formed on the insulating layer;
~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor, provided in contact with over the card substratum; and
a cover for covering at least a side of the card substratum where the antenna and the ~~thin-film~~ integrated circuit device are formed,
wherein the wiring is electrically connected to the antenna through a contact hole formed in the insulating layer, and
wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

16. (Canceled)

17. (Original) The ID card according to claim 15, wherein the cover comprises resin and is formed by a laminating method.

18. (Currently Amended) The ID card according to claim 15, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

19. (Currently Amended) An ID card comprising:
an internal substratum having a first surface and a second surface opposing to the first surface;
an antenna formed over the first surface of the internal substratum;

~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor, over the first surface of the internal substratum;

a wiring formed on the second surface of the internal substratum; and

a cover for covering around the internal substratum,

wherein the wiring is electrically connected to the antenna through a contact hole formed in the internal substratum, and

wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

20. (Canceled)

21. (Original) The ID card according to claim 19, wherein the cover comprises resin and is formed by a laminating method.

22. (Currently Amended) The ID card according to claim 19, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

23. (Currently Amended) An ID tag comprising:

~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor provided in contact with a substratum on which an antenna is formed;

an insulating layer over the antenna;

a wiring formed over the insulating layer; and

a cover for covering at least a side of the substratum where ~~in which~~ the antenna and the ~~thin-film~~ integrated circuit device are formed ~~in the substratum~~,

wherein the wiring is electrically connected to the antenna through a contact hole formed in the insulating layer, and

wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

24. (Canceled)

25. (Original) The ID tag according to claim 23, wherein the cover comprises resin and is formed by a laminating method.

26. (Currently Amended) The ID tag according to claim 23, wherein a protective layer comprising a single layer of stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

27. (Currently Amended) An ID tag comprising:
an internal substratum having a first surface and a second surface opposing to the first surface;
an antenna formed over the first surface of the internal substratum;
~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor over the first surface of the internal substratum;
a wiring formed on the second surface of the internal substratum; and
a cover for covering around the internal substratum,
wherein the wiring is electrically connected to the antenna through a contact hole formed in the internal substratum, and
wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

28. (Canceled)

29. (Original) The ID tag according to claim 27, wherein the cover comprises resin and is formed by a laminating method.

30. (Currently Amended) The ID tag according to claim 27, wherein a protective layer comprising a single layer of stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

31. (Currently Amended) An object comprising:
a ~~thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor provided in contact with a substratum on which an antenna is formed;
an insulating layer over the antenna;
a wiring formed over the insulating layer; and
a cover for covering at least a side in which the antenna and the ~~thin-film~~ integrated circuit device are formed,
wherein the wiring is electrically connected to the antenna through a contact hole formed in the insulating layer, and
wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

32. (Currently Amended) The object according to claim 31, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

33. (Currently Amended) An object comprising:
an internal substratum having a first surface and a second surface opposing to the first surface;

an antenna formed over the first surface of the internal substratum;
a ~~thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor over the first surface of the internal substratum;
a wiring formed on the second surface of the internal substratum; and
a cover for covering around the internal substratum,
wherein the wiring is electrically connected to the antenna through a contact hole formed in the internal substratum, and
wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

34. (Currently Amended) The object according to claim 33, wherein a protective layer comprising a single layer or stacked layers containing silicon oxide, silicon nitride or silicon oxynitride is formed on at least one of an upper surface and a lower surface of the ~~thin-film~~ integrated circuit device.

35. (Currently Amended) An ID label comprising:
a label substratum having a first surface and a second surface opposing to the first surface;
an antenna formed over the first surface of the label substratum;
a ~~thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor, over the first surface of the label substratum;
a wiring formed on the second surface of the label substratum;
a separating sheet provided over the first surface of the label substratum with an adhesive layer, antenna, and the ~~thin-film~~ integrated circuit device interposed therebetween,
wherein the wiring is electrically connected to the antenna through a contact hole formed in the label substratum, and

wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

36. (Currently Amended) An ID label comprising:

a label substratum;

an antenna formed over the label substratum;

an insulating layer over the antenna;

a wiring formed on the insulating layer;

~~a thin-film~~ an integrated circuit device including a ~~thin-film~~ transistor, over the label substratum;

a separating sheet provided over the label substratum with an adhesive layer, the antenna, and the insulating layer, and the ~~thin-film~~ integrated circuit device interposed therebetween,

wherein the wiring is electrically connected to the antenna through a contact hole formed in the insulating layer, and

wherein the antenna and the ~~thin-film~~ integrated circuit device are electrically connected through the wiring.

37. (New) The ID label according to claim 1, further comprising:

an adhesive layer between the wiring and the separating sheet.

38. The ID label according to claim 37,

wherein the separating sheet is configured to be peeled from the adhesive layer.

39. (New) The ID label according to claim 8, further comprising:

an adhesive layer between the label substratum and the separating sheet.

40. (New) The ID label according to claim 39,

wherein the separating sheet is configured to be peeled from the adhesive layer.